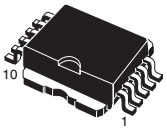
STV300NH02L

N-channel 24V - 0.8mΩ - 280A - PowerSO-10 STripFET™ Power MOSFET

Features

Type	V_{DSS}	$R_{DS(on)}$	I_D
STV300NH02L	24V	0.001Ω	280A

- $R_{DS(on)}$*Q_g industry's benchmark
- Conduction losses reduced
- Low profile, very low parasitic inductance
- Switching losses reduced



PowerSO-10

Applications

- Switching applications
  - OR-ing
- Specially designed and optimized for high efficiency DC/DC converters.

Description

This product utilizes the latest advanced design rules of ST's proprietary STripFET™ technology. This is suitable for high current OR-ing application.

Figure 1. Internal schematic diagram

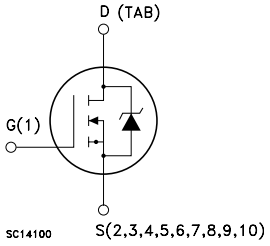


Figure 2. Connection diagram (top view)

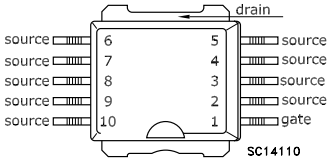


Table 1. Device summary

Order code	Marking	Package	Packaging
STV300NH02L	300NH02L	PowerSO-10	Tape & reel

Content

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (v_{gs} = 0)	24	V
V_{GS}	Gate-source voltage	± 20	V
I_D (1)	Drain current (continuous) at T_C = 25°C	280	A
I_D (1)	Drain current (continuous) at T_C = 100°C	200	A
I_{DM} (2)	Drain current (pulsed)	1120	A
P_{TOT} (3)	Total dissipation at T_C = 25°C	300	W
	Derating factor	2	W/°C
E_{AS} (4)	Single pulse avalanche energy	1.6	J
T_{stg}	Storage temperature	-55 to 175	°C
T_j	Operating junction temperature		

1. This value is limited by package
2. Pulse with limited by safe operating area
3. This value is rated according to Rthj-c
4. Starting Tj = 25°C, I_D = 60A, V_{DD} = 20V

Table 3. Thermal data

Symbol	Parameter	Value	Unit
Rthj-case	Thermal resistance junction-case max	0.5	°C/W
Rthj-amb	Thermal resistance junction-ambient max	50	°C/W

2 Electrical characteristics

(Tcase =25°C unless otherwise specified)

Table 4. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1mA, V_{GS}= 0	24			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0)	V_{DS} = Max rating, V_{DS} = Max rating, T_c=125°C			1 10	µA µA
I_{GSS}	Gate body leakage current (V_{DS} = 0)	V_{DS} = ± 20V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS}= V_{GS}, I_D = 250µA	1	1.5	2	V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS}= 10V, I_D= 80A		0.8	1	mΩ

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 15V, f = 1 MHz, V_{GS} =0		7055 3251 307		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD}= 12V, I_D= 120A, V_{GS}= 10V *(see Figure 15)*		109 30 26		nC nC nC
R_G	Gate input resistance	V_{DS} = 0V, f = 1 MHz, V_{GS} =0		4.4		Ω

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	V_{DD} = 12V, I_D = 60A R_G= 4.7Ω, V_{GS}= 10V, *(see Figure 14)*		18 275		ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time	V_{DD} = 12V, I_D = 60A R_G= 4.7Ω, V_{GS}= 10V, *(see Figure 14)*		138 94.4		ns ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM}	Source-drain current Source-drain current (pulsed)				280 1120	A A
V_{SD} (1)	Forward on voltage	I_{SD} = 120A, V_{GS} = 0			1.3	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 120A,di/dt = 100A/µs V_{DD} = 20V, T_j = 25°C *(see Figure 19)*		63 85 2.7		ns nC A
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 120A,di/dt = 100A/µs V_{DD} = 20V, T_j = 150°C *(see Figure 19)*		63 88 2.8		ns nC A

1. Pulsed: Pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 3. Safe operating area

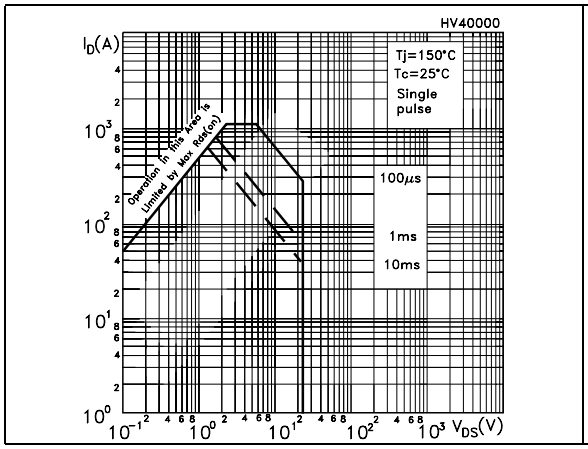


Figure 4. Thermal impedance

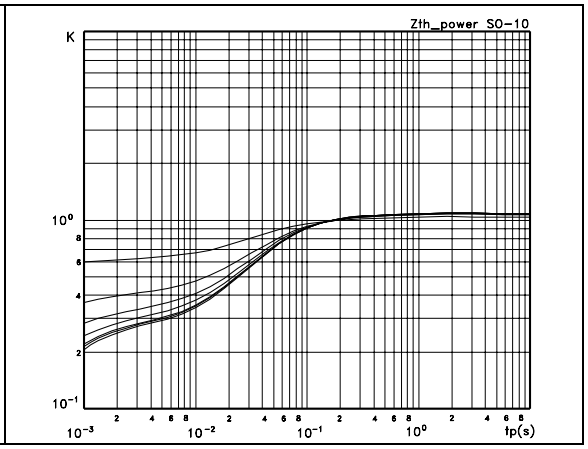


Figure 5. Output characteristics

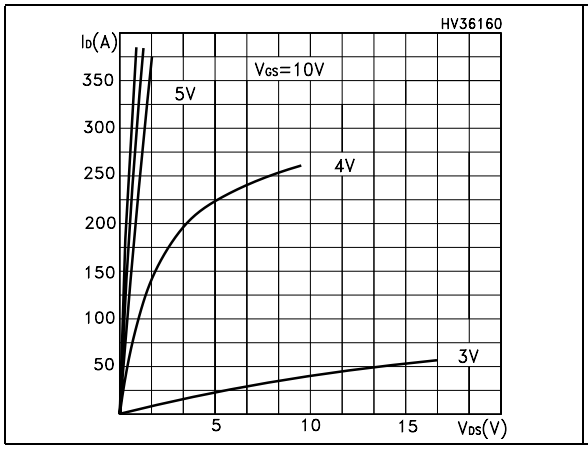


Figure 6. Transfer characteristics

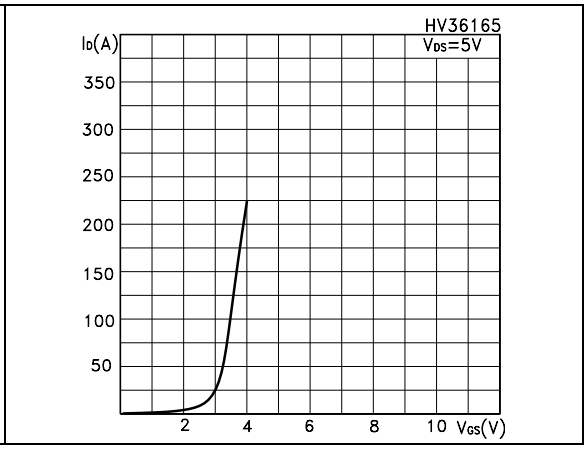


Figure 7. Static drain-source on resistance

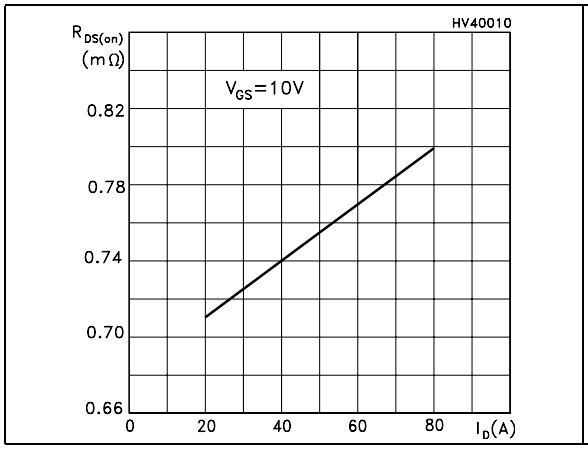


Figure 8. Normalized BV_{DSS} vs temperature

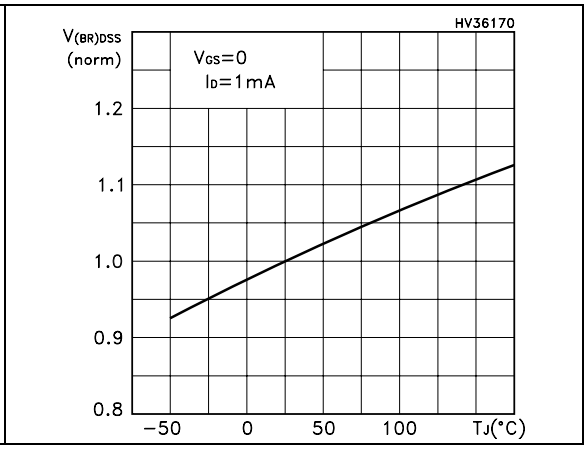


Figure 9. Gate charge vs gate-source voltage

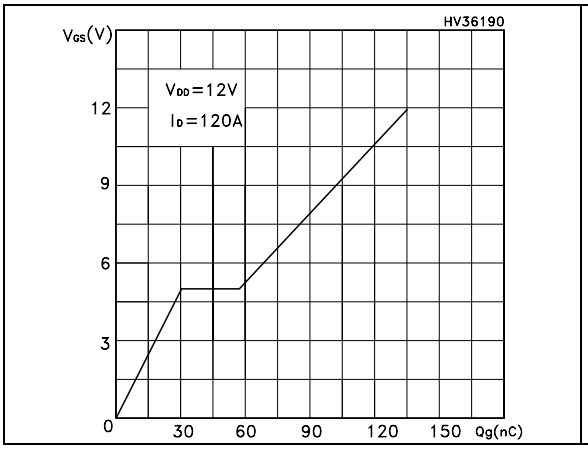


Figure 10. Capacitance variations

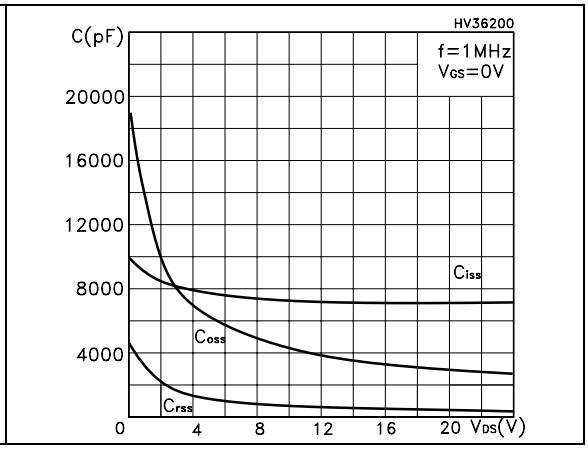


Figure 11. Normalized gate threshold voltage vs temperature

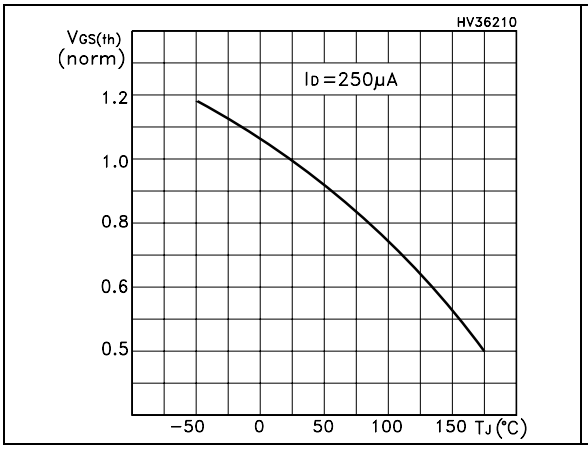


Figure 12. Normalized on resistance vs temperature

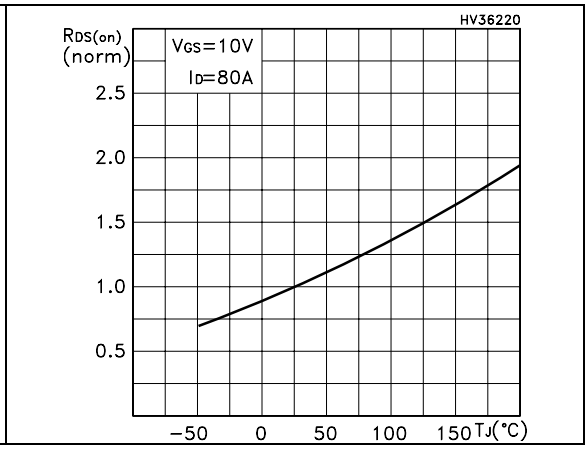
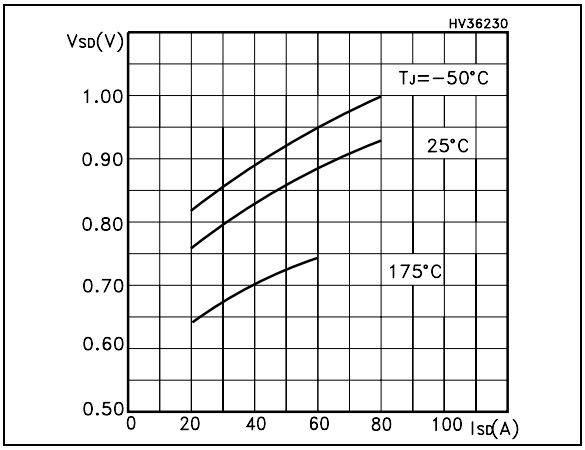


Figure 13. Source-drain diode forward characteristics



3 Test circuits

Figure 14. Switching times test circuit for resistive load

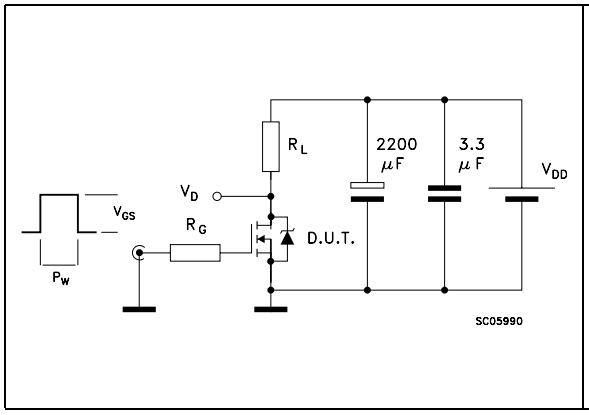


Figure 15. Gate charge test circuit

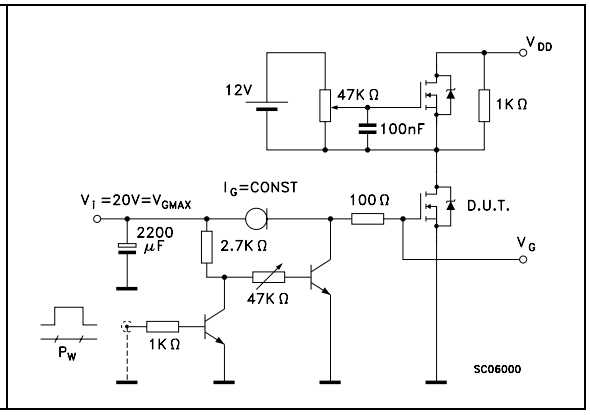


Figure 16. Test circuit for inductive load switching and diode recovery times

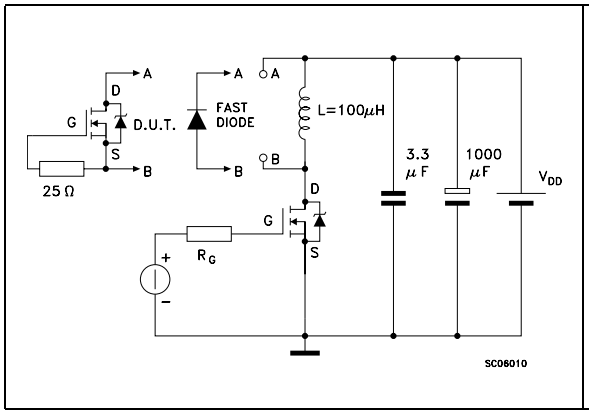


Figure 17. Unclamped inductive load test circuit

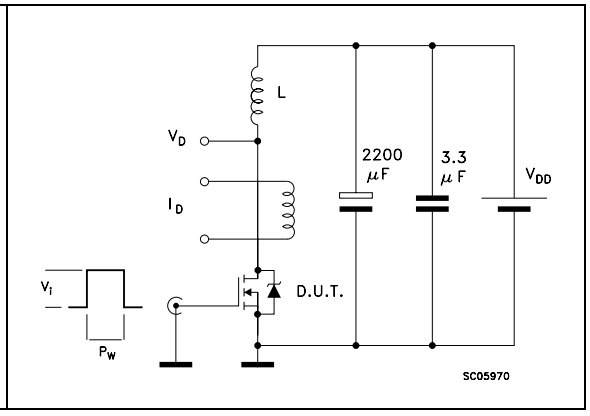


Figure 18. Unclamped inductive waveform

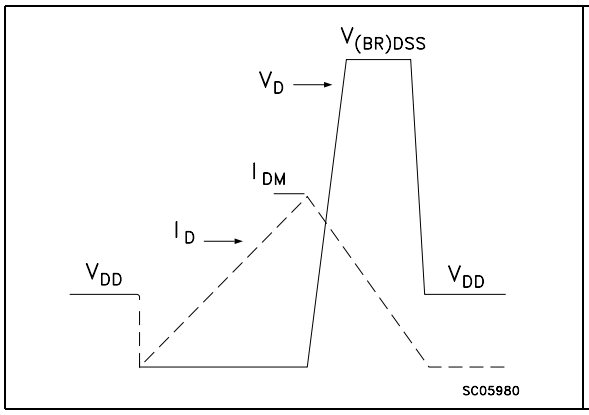
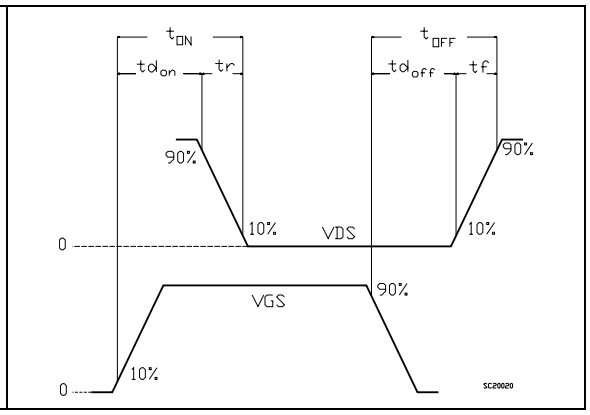


Figure 19. Switching time waveform

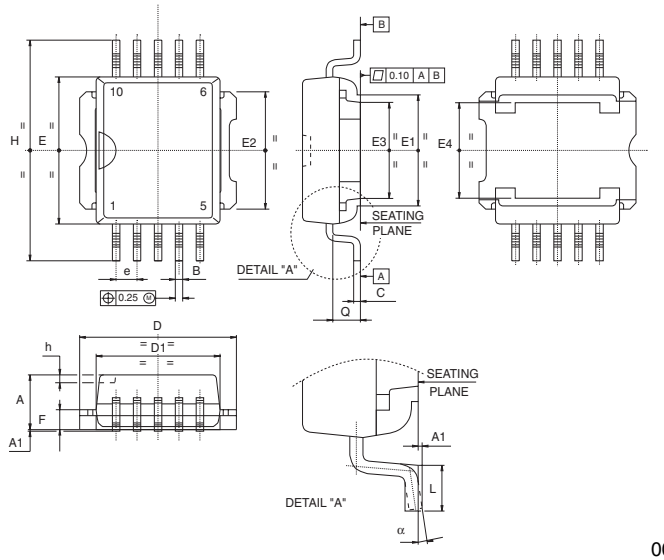


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: *www.st.com*

PowerSO-10 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	3.35		3.65	0.132		0.144
A1	0.00		0.10	0.000		0.004
B	0.40		0.60	0.016		0.024
C	0.35		0.55	0.013		0.022
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.300
e		1.27			0.050	
E	9.30		9.50	0.366		0.374
E1	7.20		7.40	0.283		0.291
E2	7.20		7.60	0.283		0.300
E3	6.10		6.35	0.240		0.250
E4	5.90		6.10	0.232		0.240
F	1.25		1.35	0.049		0.053
h		0.50			0.002	
H	13.80		14.40	0.543		0.567
L	1.20		1.80	0.047		0.071
q		1.70			0.067	
α	0°		8°			



0068039-C

5 Revision history

Table 8. Revision history

Date	Revision	Changes
08-Feb-2007	1	First release
13-Sep-2007	2	New section has been added: *2.1: Electrical characteristics (curves)*

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